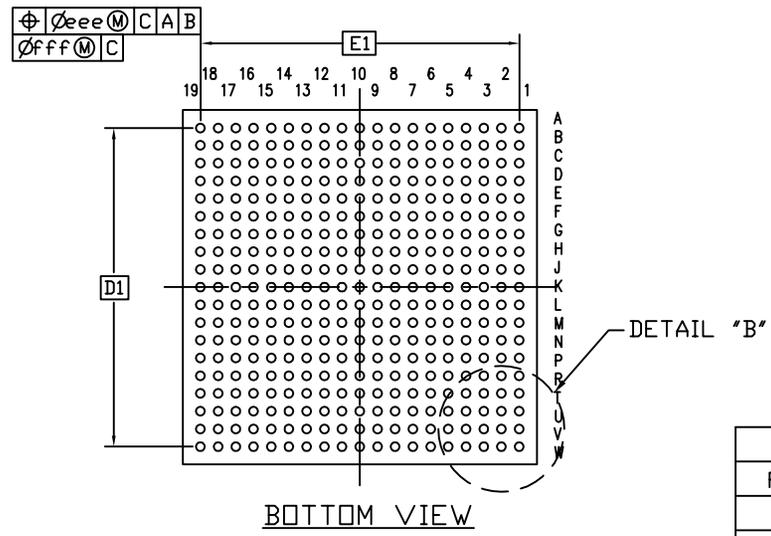
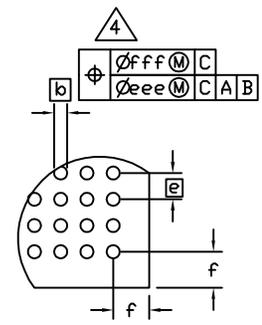


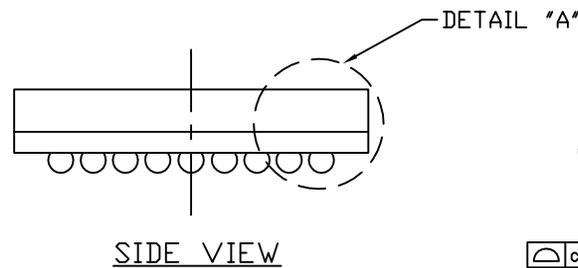
TOP VIEW



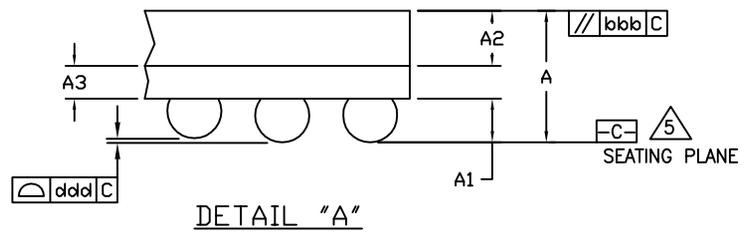
BOTTOM VIEW



DETAIL "B"



SIDE VIEW



DETAIL "A"

DIMENSIONAL REFERENCES			
REF.	MIN.	NOM.	MAX.
A	1.30	1.40	1.50
A1	0.35	0.40	0.45
A2	0.65	0.70	0.75
A3	0.32 REF		
D	15.80	16.00	16.20
D1	14.40 BSC		
E	15.80	16.00	16.20
E1	14.40 BSC		
b	--	0.5	--
e	0.8 BSC		
f	--	0.80	--
aaa	--	--	0.15
bbb	--	--	0.20
ddd	--	--	0.15
eee	--	--	0.15
fff	--	--	0.08
M	19		
N	361		
Pkg. Code: X36166MK+1			

- NOTES:
- ALL DIMENSIONS ARE IN MILLIMETERS.
 - 'e' REPRESENTS THE BASIC SOLDER BALL PITCH.
 - 'M' REPRESENTS THE BASIC SOLDER BALL MATRIX SIZE. 'N' IS THE NUMBER OF ATTACHED SOLDER BALLS.
 - 'b' IS MEASURABLE AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO THE PRIMARY DATUM $\square C \square$.
 - PRIMARY DATUM $\square C \square$ AND THE SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - THE PACKAGE SURFACE SHALL BE MATTE FINISH CHARMILLES 24 TO 27.
 - THE OVERALL PACKAGE THICKNESS "A" ALREADY CONSIDERS COLLAPSED BALLS.
 - REFERENCE JEDEC MO-205.
 - MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
 - ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.
 - ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.

-DRAWING NOT TO SCALE-


maxim integrated™

TITLE:
PACKAGE OUTLINE,
361 BALL CSBGA, 16x16x1.4 mm

APPROVAL SCOTT SCHROEDER 04/17/13	DOCUMENT CONTROL NO. 21-0718	REV. A	1/1
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